PCN Number:	201	20140320003 PCN Date: 04/03/2014						04/03/2014		
Title: Design Change (for TPS54623RHLR and TPS54623RHLT Devices)										
Customer Contact:	ustomer Contact: PCN		Phone:	+1(2	(214)480-6037		7 Dept:	Quality Services		
Proposed 1 st Ship Da		07/03/2	014	Estin			d Sample	Date provided at		
		07/03/2		T		Availab		sample request		
Change Type:										
Assembly Site		Assembly Process				Assembly Materials				
Design		Electrical Specification						Mechanical Specification		
Test Site Wafer Bump Site		Packing/Shipping/Labeling			ling	\underline{H}	Test Process Wafer Bump Process			
Wafer Fab Site		Wafer Bump Material			\square	Wafer Fab Process				
									10035	
Part number change PCN Details										
Description of Char	ge:				-					
This notification is to inform of a design change for TPS54623RHLR and TPS54623RHLT devices. This design change does not affect the device's guaranteed datasheet specifications or electrical performance. Affected devices are listed in "Product Affected" section. The table below describes changes that were made:										
Description of Change Benefit of Change										
All layer change to improve EcoMode Feature. The design change affects about 5% of the IC circuit in LDO-Error Amplifier block. Adding an NMOS in LDO and a logic inverter in Error Amplifier.										
Reason for Change:										
To address EcoMode issue.										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):										
None										
Changes to product identification resulting from this PCN:										
None										
Product Affected:										
TPS54623RHLR	TP	S54623RF	ILT							

Qualification Data: Approved 3/14/2014							
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.							
Qual Vehicle 1: TPS54623							
Package/Die Construction Details							
Assembly Site:	: CLARK AT		# Pins-Designator, Family:		14-RHL, QFN		
Die Revision: A			Package Type:	QF	QFN/SON		
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test			nditions		Sample Size (PASS/FAIL)		
Electrical Characterization, side by side					PASS		
Latch-up			r JESD78)		6/0		
Life Test			5C (168 Hrs)		80/0		
ESD CDM			250V		3/0		
ESD HBM			1000V		3/0		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com